

SMD contact springs are ideal for automatic assembly on printed circuit boards. They are soldered by the standard reflow-soldering process.

The standard basic material used for this SMD contact spring is copper titanium. However, other materials can also be supplied.

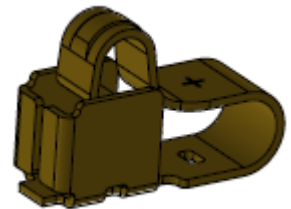
As standard, SMD springs are gold-plated (AU). They can be supplied in a wide range of dimensions and shapes.

- Ideal for automatic assembly
- Standard basic material: YCUT-FX-EH
- Standard plating: AU
- Available in different dimensions and types
- Almost unlimited working life

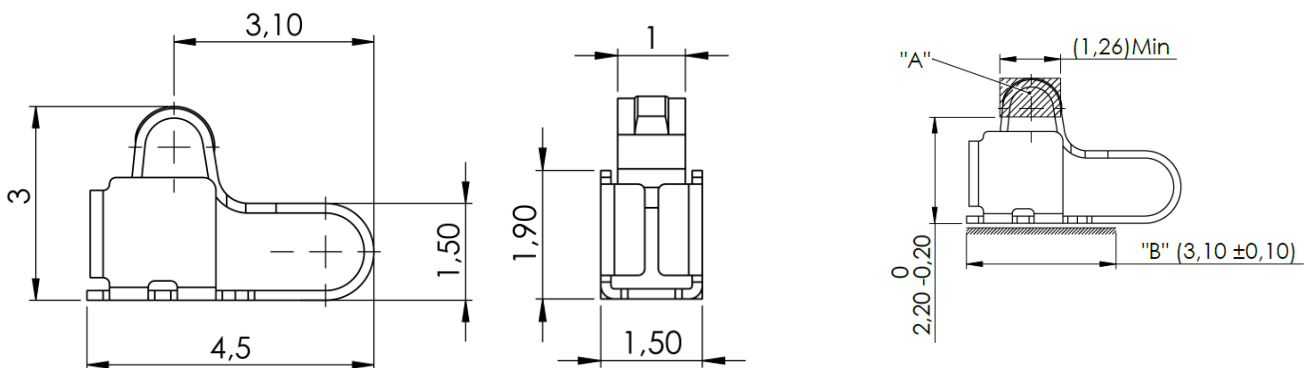


PRODUCT SPECIFICATIONS

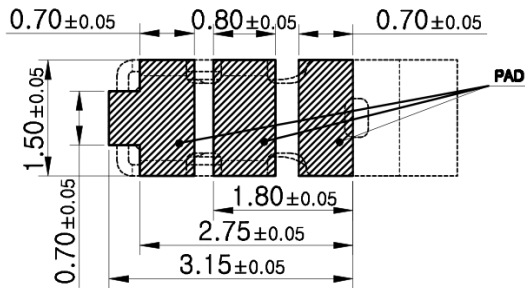
PROPERTY		VALUE / TOLERANCE
Thickness		0,15 mm
Width		1,50 mm ±0,10
Length		4,50 mm ±0,10
Height		3,00 mm ±0,10
Basic material		Copper titanium (YCUT-FX-EH)
Plating	Barrier layer Ni	1,5µm – 4,00µm
	Contact area „A“ AU	0,1 µm
	SMD area „B“ AU	0,05 µm



DIMENSIONS (mm)



RECOMMENDED RESERVED AREA ON THE PCB (mm)



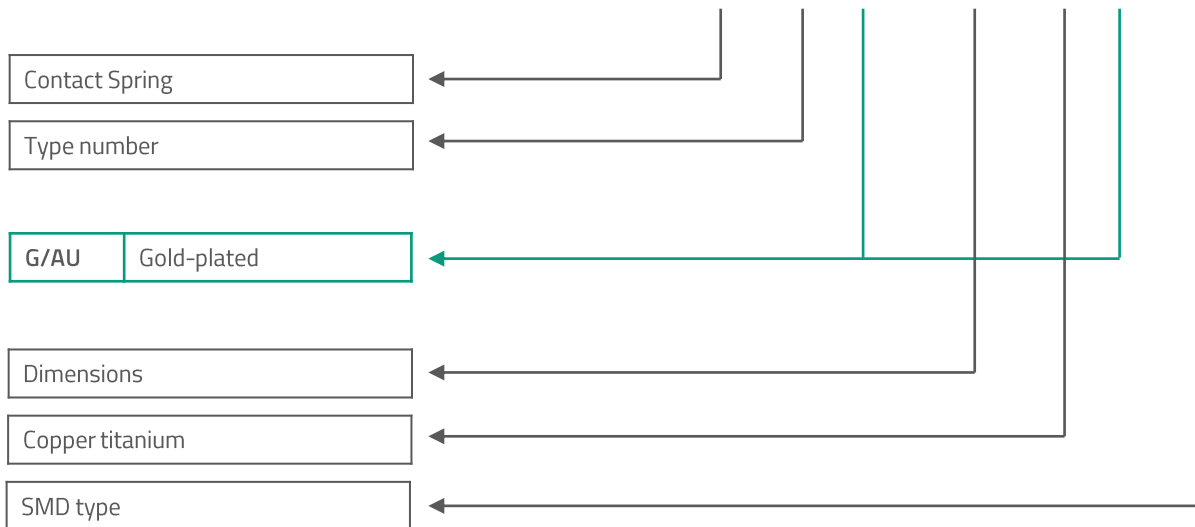
DISCLAIMER

This is only a recommendation based on information available to mtc at the time of printing. Actual land pattern can be significantly different due to various materials and processes used in PCB assembly. mtc makes no representation or warranty of performance based on the recommended land pattern.

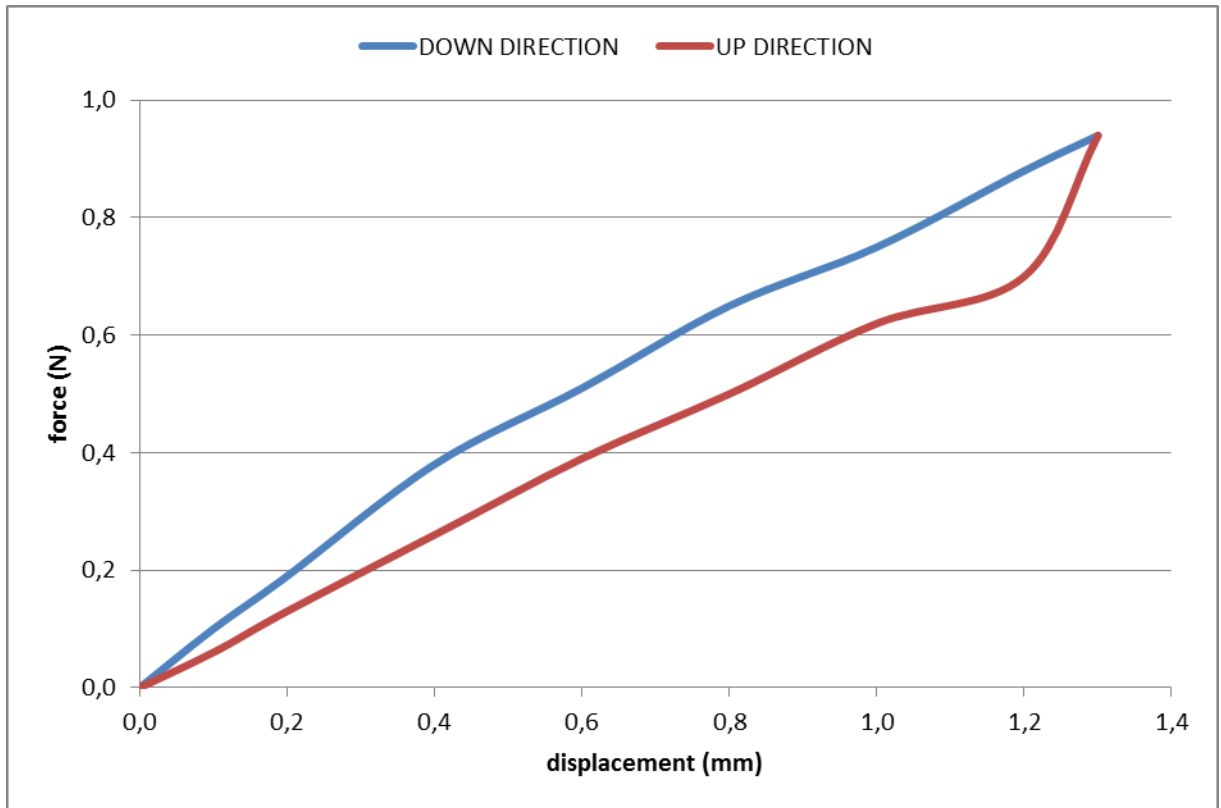
RECOMMENDED PAB LAOUT

BUILDING AN ITEM NUMBER

FCB-26YG1545030T-AU-SMD

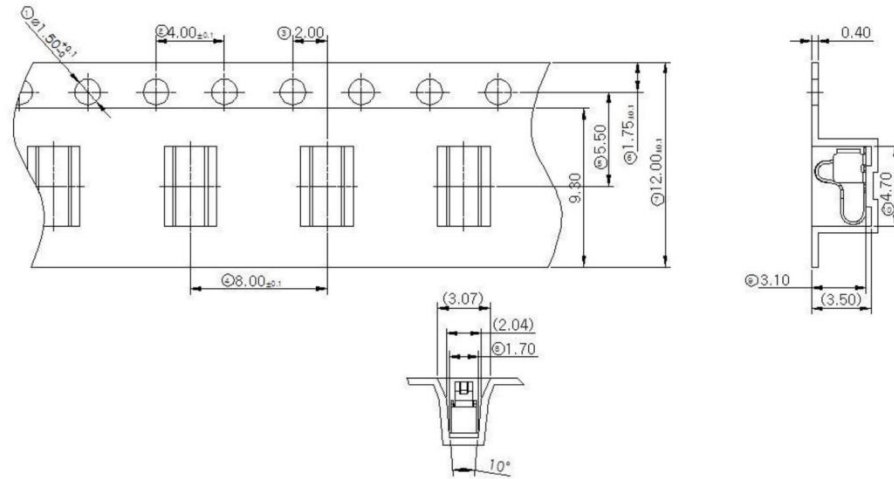


FORCE DEFLECTION DIAGRAM



NOTE | * Only valid for gold-plated version

PACKING SPECIFICATION – TAPE AND REEL (mm)



- Component packing 330*80*12 mm reel: 2.500 pcs
- Cover Tape: PS. 9,3mm * 480m